

## Description

The HSBA90N02 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

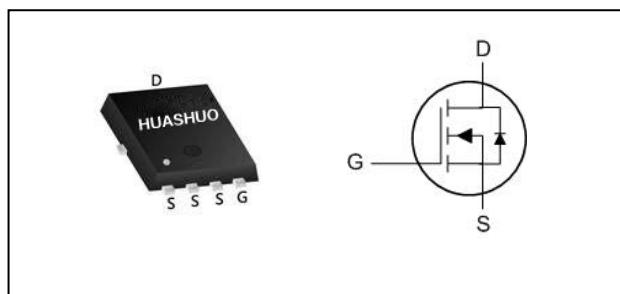
The HSBA90N02 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Battery protection
- Power management

## Product Summary

$V_{DS}$	20	V
$R_{DS(ON),typ}$	2.9	$m\Omega$
$I_D$	90	A

## PRPAK5\*6 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	90	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	63	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	350	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	195	mJ
$P_D @ T_c = 25^\circ C$	Total Power Dissipation <sup>4</sup>	60	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	2.1	$^\circ C/W$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	20	---	---	V
△BV <sub>DSS</sub> /△T <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.028	---	V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	---	2.9	3.8	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =15A	---	3.4	4.5	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	0.5	---	1.0	V
△V <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-6.16	---	mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fS</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =20A	---	99	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	1.7	---	Ω
Q <sub>g</sub>	Total Gate Charge (4.5V)	V <sub>DS</sub> =20V, V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	37	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	5.5	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	8.2	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =10V, V <sub>GS</sub> =4.5V, R <sub>G</sub> =3.3Ω I <sub>D</sub> =20A	---	10	---	ns
T <sub>r</sub>	Rise Time		---	5.5	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	49	---	
T <sub>f</sub>	Fall Time		---	5.3	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=1MHz	---	3050	---	pF
C <sub>oss</sub>	Output Capacitance		---	360	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	40	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	90	A
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>		---	---	350	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =20A, T <sub>J</sub> =25°C	---	---	1.0	V
t <sub>rr</sub>	Reverse Recovery Time	IF=20A, dI/dt=100A/μs, T <sub>J</sub> =25°C	---	16	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge		---	6.6	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=10V,V<sub>GS</sub>=10V,L=0.5mH
- 4.The power dissipation is limited by 175°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.



**HUASHUO**  
SEMICONDUCTOR

**HSBA90N02**

**N-Ch 20V Fast Switching MOSFETs**

### Typical Characteristics

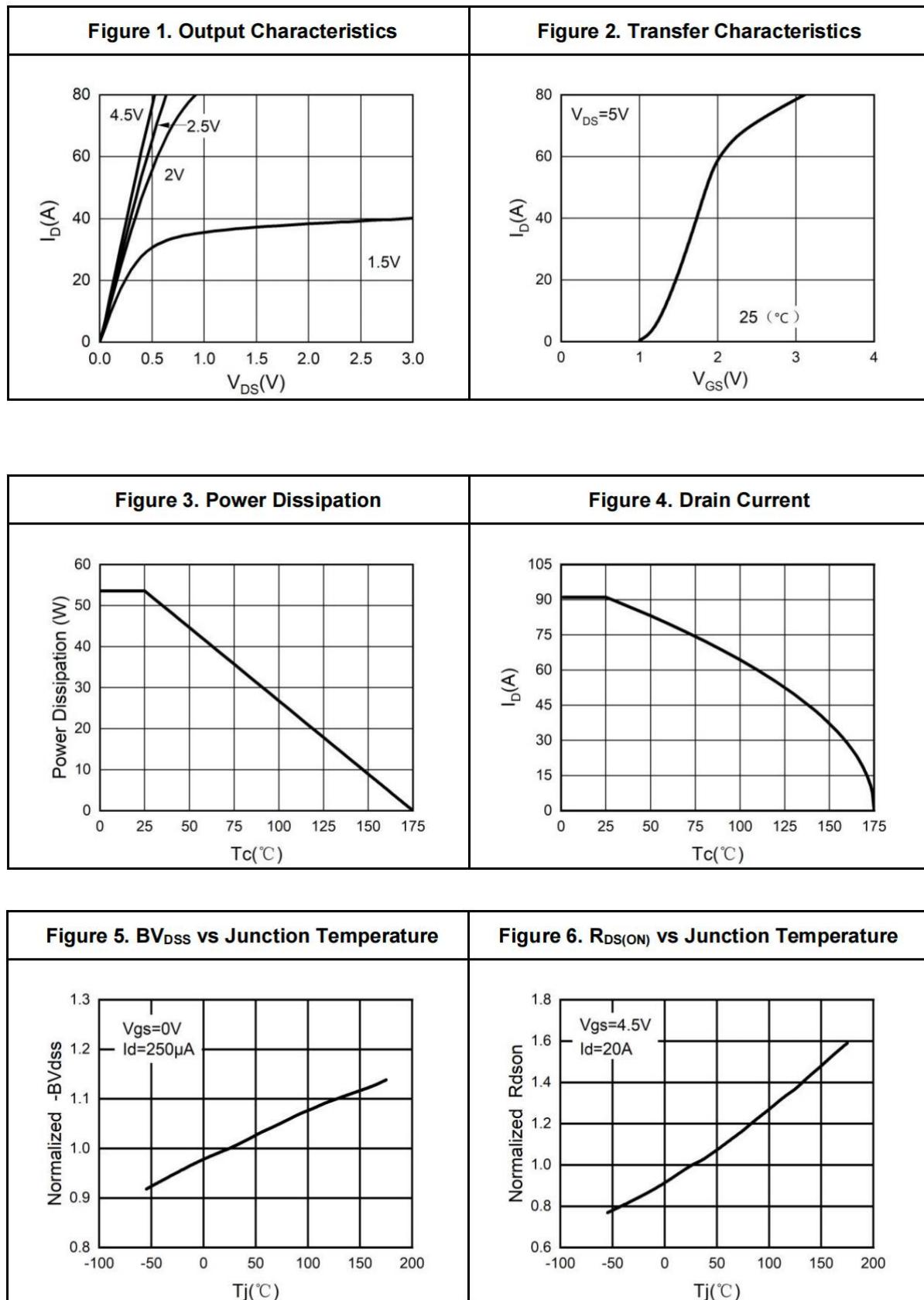




Figure 7. Gate Charge Waveforms

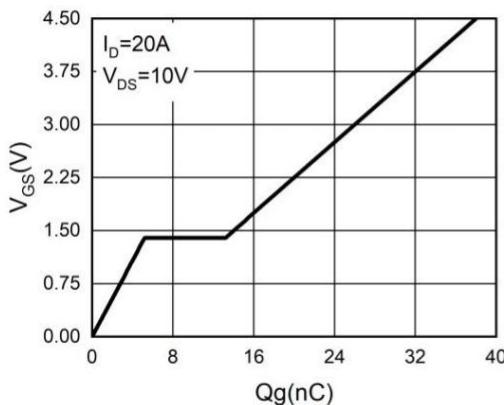


Figure 8. Capacitance

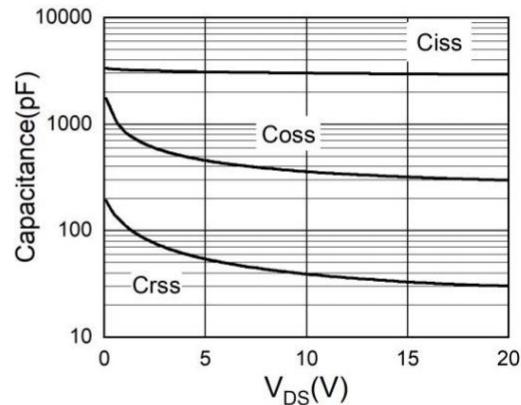


Figure 9. Body-Diode Characteristics

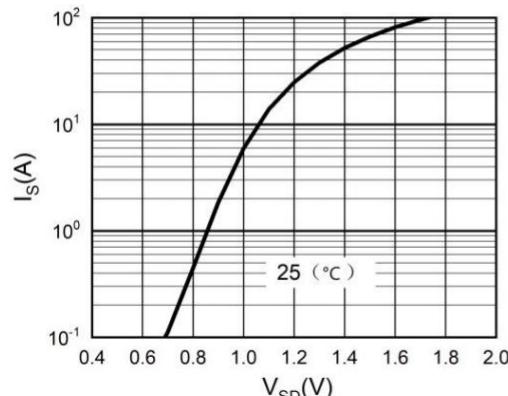
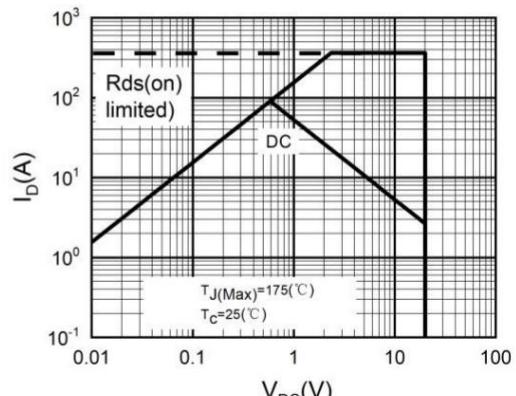


Figure 10. Maximum Safe Operating Area





## Ordering Information

Part Number	Package code	Packaging
HSBA90N02	PRPAK5*6	3000/Tape&Reel

